

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3209468

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MASASHI IKAWA	01/27/2015
EIKO OKAMOTO	01/27/2015
HIROSHI ONOMOTO	01/27/2015
JITSUO HIROHATA	01/27/2015
YUJI MATSUBARA	01/27/2015
HIDEKI MASUDA	01/27/2015

RECEIVING PARTY DATA

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State/Country:	JAPAN
Postal Code:	100-8253
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Street Address:	2-1, SAKADO 3-CHOME, TAKATSU-KU
City:	KAWASAKI-SHI, KANAGAWA
State/Country:	JAPAN
Postal Code:	213-0012

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14419293

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	7412/134410
NAME OF SUBMITTER:	LOIS FORD
SIGNATURE:	/Lois Ford/
DATE SIGNED:	02/03/2015
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 4 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif	

Please return signed/recorded to:

Fitch, Even, Tabin & Flannery LLP
1250 23rd Street, NW, Suite 410
Washington, DC 20037

13P00020-15 04P 00000
For inventions made outside USA
executed with or after application
Atty. Dkt. 7412/134410

USA Patent Appln.
Sole or Joint

**NONPROVISIONAL ASSIGNMENT WITH DECLARATION NONPROVISIONAL
OF NONPROVISIONAL APPLICATION**

In consideration of the sum of Ten Dollars (\$10.00) and other good and valuable consideration paid to each of the undersigned, to wit:

INSERT (1) Masashi IKAWA (2) Eiko OKAMOTO
NAME(S) OF INVENTOR(S)
(3) Hiroshi ONOMOTO (4) Jitsuo HIROHATA
(5) Yuji MATSUBARA (6) Hideki MASUDA

the receipt and sufficiency of which are hereby acknowledged by the undersigned who at the request of, hereby sell(s), assign(s) and transfer(s) unto:

INSERT Mitsubishi Rayon Co., Ltd.
NAME(S) OF ASSIGNEE(S) 1-1, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-8253 Japan
& ADDRESS(ES) _____

INSERT Kanagawa Academy of Science and Technology
NAME(S) OF ASSIGNEE(S) 2-1, Sakado 3-chome, Takatsu-ku, Kawasaki-shi, Kanagawa 213-0012 Japan
& ADDRESS(ES) _____

(hereinafter designated ASSIGNEE@) the entire right, title and interest for the United States of America, in the invention and all applications including any divisions, continuations, substitutes, reissues, and reexaminations thereof, and all resulting patents, known as:

METHOD OF MANUFACTURING MOLD, AND MOLDED ARTICLE HAVING FINE RELIEF STRUCTURE ON SURFACE AND METHOD OF MANUFACTURING THE SAME

NOTE (Complete line A, B and/or C) for which an application for Letters Patents of the United States of America:
(A) was filed on even date herewith
(B) executed on _____
(C) was filed on my behalf as PCT/JP2013/071223, filed August 6, 2013,

AND I hereby Declare (1) the above-identified application was made or authorized to be made by me; (2) I have reviewed the above-identified application and understand the contents of the above-identified specification; (3) I acknowledge the duty to disclose information which is known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56; and (4) I believe I am the original inventor or an original joint inventor of a claimed invention in this application. I hereby acknowledge that any willful false statement in the aforesaid Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both;

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives;

AND the undersigned agree(s) that the attorney of record in said application shall hereinafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE=S full protection and title in and to the invention hereby transferred.

NOTE)) The undersigned hereby authorize(s) Fitch, Even, Tabin & Flannery of the above address to insert hereon any further identification necessary or desirable for recordation of this document.

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Inventor's signature: Masashi IKAWA
Date: January 27, 2015

13P00060-03
25/1/2015

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KP121-117-PC1
05P 56799

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NAME(S) OF
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Name: Masashi IKAWA
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